Tyrone Camarero Specifications

Tyrone

Camerero: SDI300A2G-36

Key Feature

3U Intel DP Edge Data Center System with Up to 10 PCIe 5.0 x16 slots + Up to 14 E1.S NVMe Drives

High Performance Computing, AI/Deep Learning Training, Industrial Automation, Retail, Healthcare, Conversational AI,Business Intelligence & Analytics,Drug Discovery, Climate and Weather Modeling, Finance & Economics, Edge AI Inferencing

- Dual Intel® Xeon® 6900-Series Processors with P-cores up to 500W
- 24 DIMMs supporting up to 6TB 6400MT/s DDR5 RDIMM or 3TB 8800MT/s DDR5 MRDIMM
- Up to 10 PCle 5.0 x16 FHFL or 20 PCle 5.0 x8 FHFL slots
- 6/14 hot-swap E1.S NVMe drive bays or 4/6 hot-swap 2.5" NVMe drive bays
- 3x 3200W or 2700W Redundant (2+1) Titanium Level power supplies
- Support up to 8 Double Width GPU or 19 Single Width GPU





Processor/Cache		
Processor	Dual Socket BR (LGA-7529), Intel® Xeon® 6900 series processors with P-cores	
Chipset		
Chipset	System on Chip	
System Memory		
Memory Capacity	Slot Count: 24 DIMM slots/2 Channels Max Memory (1DPC): 3TB 6400MT/s ECC DDR5 RDIMM, Max Memory (2DPC): 6TB 5200MT/s ECC DDR5 RDIMM	
Expansion Slot		
PCI-Express	8 PCle 5.0 x16 (in x16) FHFL double-width slots Option A: 8 PCle 5.0 x16 (in x16) FHFL double-width slots, 2 PCle 5.0 x16 (in x16) FHFL slots Option B: 20 PCle 5.0 x8 (in x16) FHFL slots	
GPU		
GPU	Up to 8 double-width or 19 single-width GPUs	
Integrated Onboard:		
LAN	1 RJ45 1 GbE Dedicated BMC LAN port	
Ports	2 USB 3.2 Gen1 Type-A ports, 1 VGA port, 1 TPM header	

Add-on Options		
Raid Card	None	
Optical Drive	e None	
Drive bays		
HDD Bays	Option A: Total 6 bays, 6 front hot-swap E1.S PCle 5.0 x4 NVMe* drive bays Option B: Total 14 bays, 14 front hot-swap E1.S PCle 5.0 x4 NVMe* drive bays Option C: Total 4 bays, 4 front hot-swap 2.5" PCle 5.0 x4 NVMe* drive bays Option D: Total 6 bays, 6 front hot-swap 2.5" PCle 5.0 x4 NVMe* drive bays M.2: 2 M.2 PCle 5.0 x2 NVMe slots (M-key)	
Power Supply		
Power Supp	3x 2700/3200W Redundant (2 + 1) Titanium Level (96%) Hot-plug power supplies	
Cooling System		
5 Front 8cm Fan(s), 6 Internal 6cm Fan(s)		
Form Factor		
Form Factor	r 3U Rackmount	
Dimensions		
Dimensions	Height : 5.2" (132.1 mm), Width : 17.26" (438.4 mm), Depth: 31.5" (800 mm)	
Email: Info@tyronesystems.com For more/current product information, Visit www.tyronesystems.com		

Intel, the Intel logo, the Intel Inside logo, Xeon, and Intel Xeon Phi are trademarks of Intel Corporation in the U.S and/Or other Countries

Specifications subject to change without notice. Picture used for representation purpose only and the actual product may differ in looks. All other brands and names are the properties of their respective owners